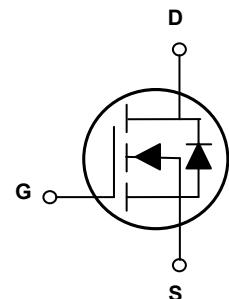
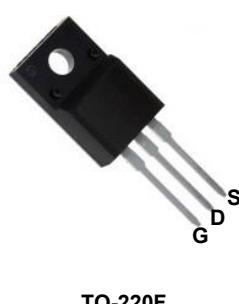


Main Product Characteristics

| | |
|--------------|--------|
| V_{DS} | 250V |
| $R_{DS(ON)}$ | 18.5mΩ |
| I_D | 80A |



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFU2580 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Max. | Unit |
|---|-----------------|-------------|---------------------------|
| Drain-Source Voltage | V_{DS} | 250 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 80 | A |
| Drain Current-Continuous($T_C=100^\circ\text{C}$) | | 56.6 | A |
| Drain Current-Pulsed | I_{DM} | 320 | A |
| Maximum Power Dissipation | P_D | 50 | W |
| Derating Factor | | 3 | W/ $^\circ\text{C}$ |
| Single Pulse Avalanche Energy ⁵ | E_{AS} | 1200 | mJ |
| Thermal Resistance, Junction-to-Case ² | $R_{\theta JC}$ | 0.33 | $^\circ\text{C}/\text{W}$ |
| Storage Temperature Range | T_{STG} | -55 To +175 | $^\circ\text{C}$ |
| Operating Junction Temperature Range | T_J | -55 To +175 | $^\circ\text{C}$ |

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|--|----------------------------|--|------|------|-----------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$ | 250 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}}=250\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | 1 | μA |
| Gate-Source Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$ | - | - | ± 100 | nA |
| On Characteristics³ | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$ | 2.5 | - | 4.5 | V |
| Drain-Source On-State Resistance | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=10\text{V}, I_{\text{D}}=40\text{A}$ | - | 16 | 18.5 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{DS}}=10\text{V}, I_{\text{D}}=40\text{A}$ | 70 | - | - | S |
| Gate Resistance | R_{G} | - | - | 6.5 | - | Ω |
| Dynamic Characteristics⁴ | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=125\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$ | - | 5400 | - | pF |
| Output Capacitance | C_{oss} | | - | 329 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 12 | - | |
| Switching Characteristics⁴ | | | | | | |
| Turn-On Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}}=125\text{V}, R_{\text{G}}=4.7\Omega$ $V_{\text{GS}}=10\text{V}, I_{\text{D}}=40\text{A}$ | - | 18 | - | nS |
| Turn-On Rise Time | t_{r} | | - | 26 | - | |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 41 | - | |
| Turn-Off Fall Time | t_{f} | | - | 11 | - | |
| Total Gate Charge | Q_{g} | $V_{\text{DS}}=125\text{V}, I_{\text{D}}=40\text{A}, V_{\text{GS}}=10\text{V}$ | - | 76.7 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 22.7 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 20 | - | |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage ³ | V_{SD} | $V_{\text{GS}}=0\text{V}, I_{\text{S}}=80\text{A}$ | - | - | 1.2 | V |
| Diode Forward Current ² | I_{S} | - | - | - | 80 | A |
| Reverse Recovery Time | t_{rr} | $T_j=25^\circ\text{C}, I_F=I_S=40\text{A}, \frac{di}{dt}=100\text{A}/\mu\text{s}^3$ | - | 140 | - | nS |
| Reverse Recovery Charge | Q_{rr} | | - | 600 | - | nC |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production.
5. EAS condition : $T_j=25^\circ\text{C}, V_{\text{DD}}=50\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_{\text{g}}=25\Omega$.

Typical Electrical and Thermal Characteristic Curves

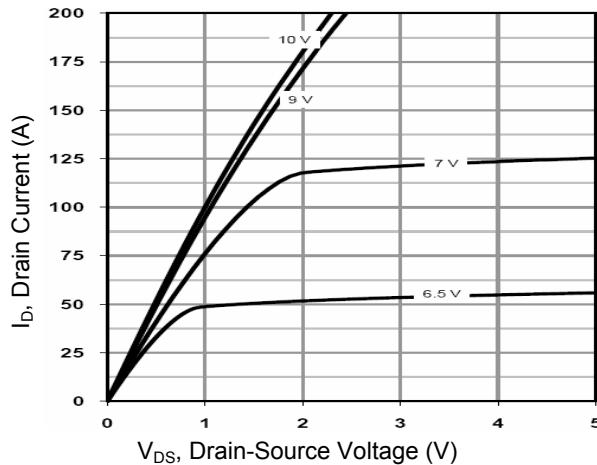


Figure 1. Output Characteristics

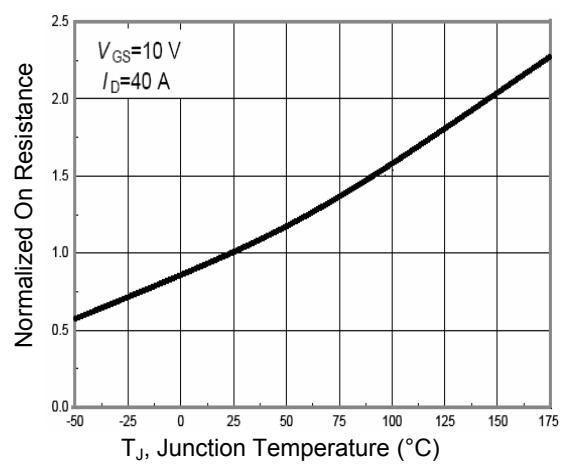


Figure 2. $R_{DS(on)}$ -Junction Temperature

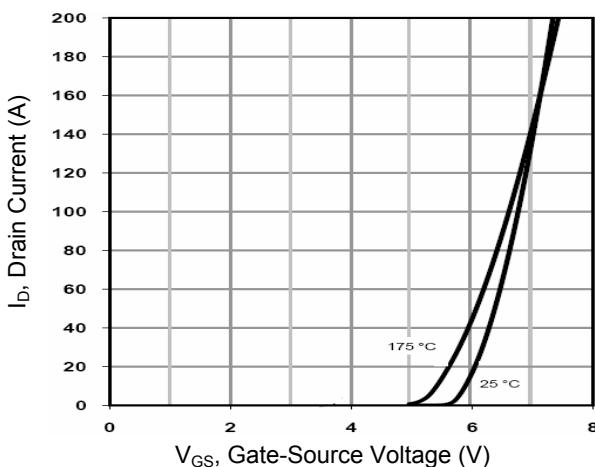


Figure 3. Transfer Characteristics

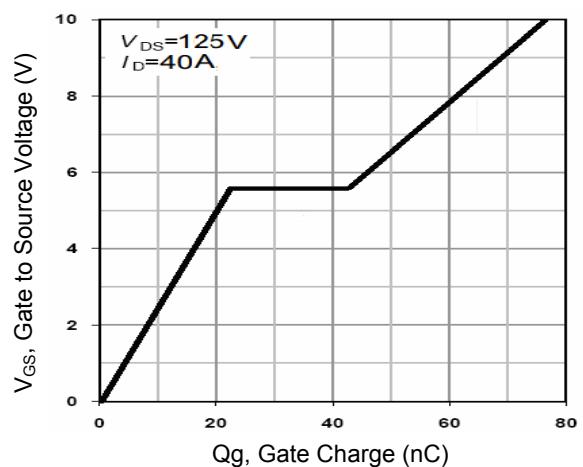


Figure 4. Gate Charge

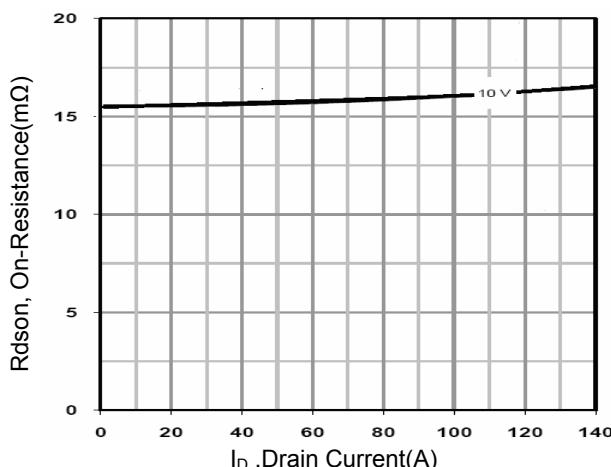


Figure 5. $R_{DS(on)}$ -Drain Current

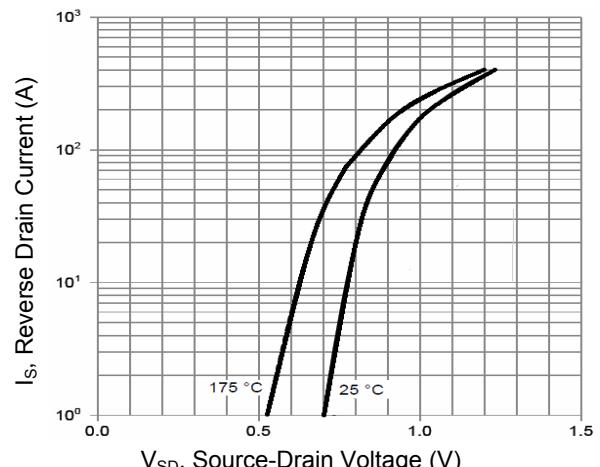


Figure 6. Source-Drain Diode Forward

Typical Electrical and Thermal Characteristic Curves

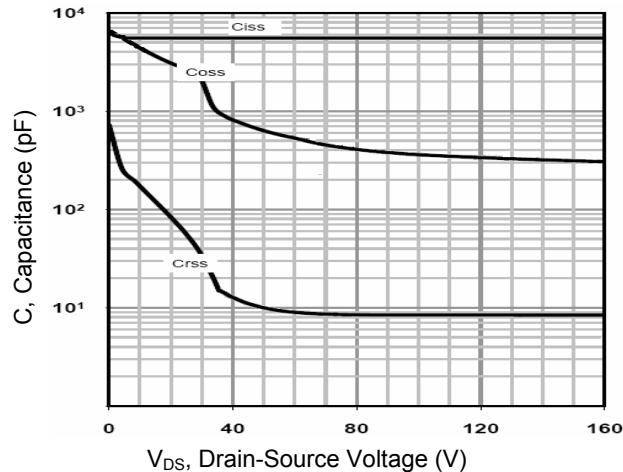


Figure 7. Capacitance vs. V_{DS}

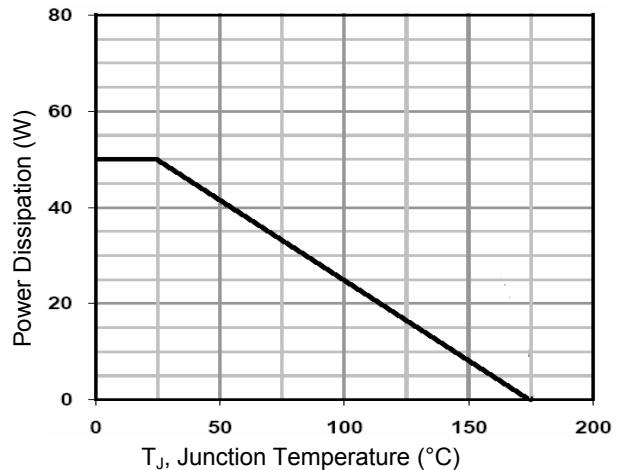


Figure 8. Power De-rating

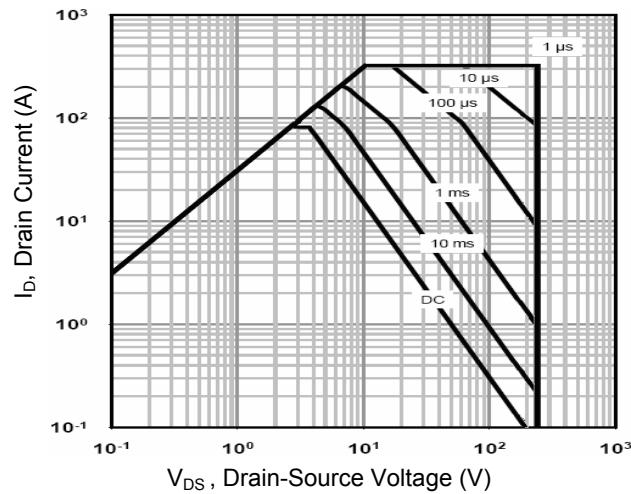


Figure 9. Safe Operation Area

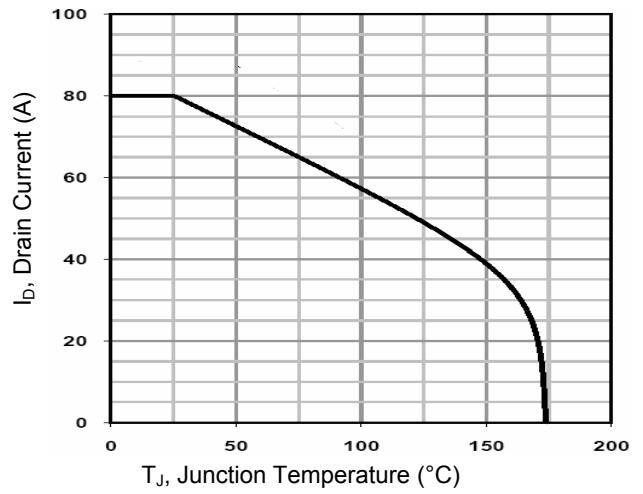


Figure 10. Current De-rating

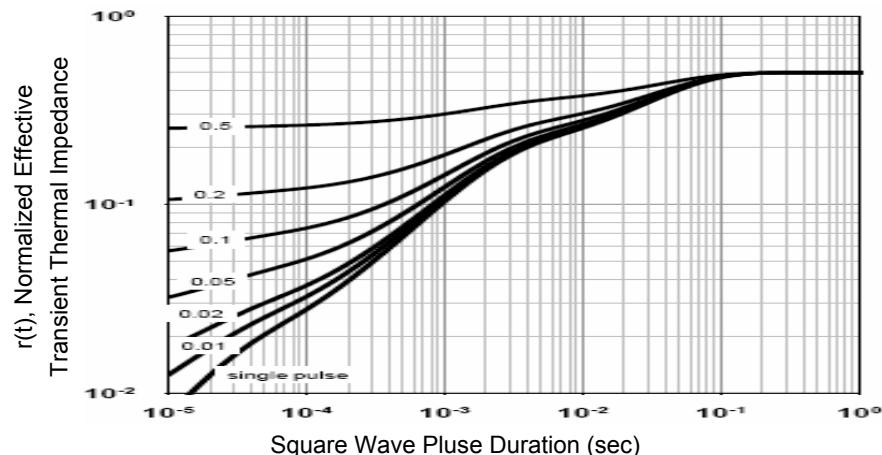
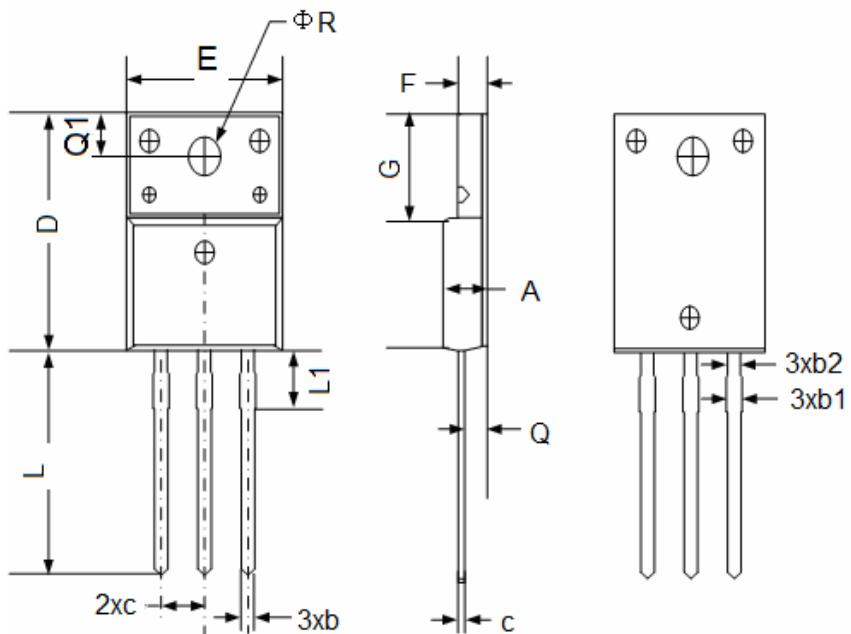


Figure 11. Normalized Maximum Transient Thermal Impedance

Package Outline Dimensions (TO-220F)



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|------|
| | Min. | Max. | Min. | Max. |
| A | 4.50 | 4.83 | 0.18 | 0.19 |
| b | 0.70 | 0.91 | 0.03 | 0.04 |
| b1 | 1.20 | 1.47 | 0.05 | 0.06 |
| b2 | 1.10 | 1.38 | 0.04 | 0.05 |
| c | 0.45 | 0.63 | 0.02 | 0.02 |
| D | 15.67 | 16.07 | 0.62 | 0.63 |
| e | 2.54 BSC | | 0.10 BSC | |
| E | 9.96 | 10.36 | 0.39 | 0.41 |
| F | 2.34 | 2.74 | 0.09 | 0.11 |
| G | 6.48 | 6.90 | 0.26 | 0.27 |
| L | 12.68 | 13.30 | 0.50 | 0.52 |
| L1 | 3.13 | 3.50 | 0.12 | 0.14 |
| Q | 2.56 | 2.93 | 0.10 | 0.12 |
| Q1 | 3.20 | 3.40 | 0.13 | 0.13 |
| ΦR | 3.08 | 3.28 | 0.12 | 0.13 |